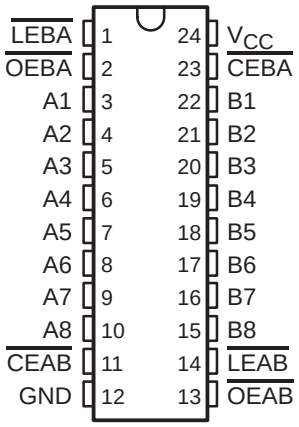
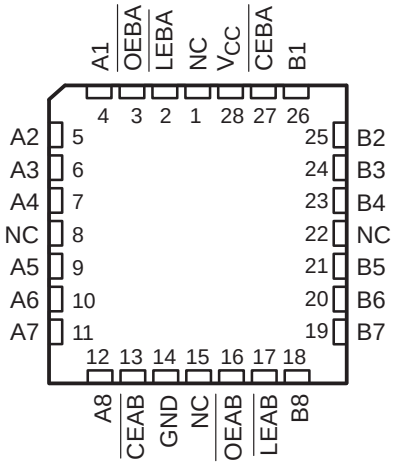
- **State-of-the-Art *EPIC*-II*B*™ BiCMOS Design Significantly Reduces Power Dissipation**
- **ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)**
- **Typical V_{OLP} (Output Ground Bounce) < 1 V at V_{CC} = 5 V, T_A = 25°C**
- **High-Drive Outputs (–32-mA I_{OH}, 64-mA I_{OL})**
- **Package Options Include Plastic Small-Outline (DW), Shrink Small-Outline (DB), and Thin Shrink Small-Outline (PW) Packages, Ceramic Chip Carriers (FK), Ceramic Flat (W) Package, and Plastic (NT) and Ceramic (JT) DIPs**

SN54ABT543A . . . JT OR W PACKAGE
SN74ABT543A . . . DB, DW, NT, OR PW PACKAGE
(TOP VIEW)



SN54ABT543A . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The ’ABT543A octal transceivers contain two sets of D-type latches for temporary storage of data flowing in either direction. Separate latch-enable ($\overline{\text{LEAB}}$ or $\overline{\text{LEBA}}$) and output-enable ($\overline{\text{OEAB}}$ or $\overline{\text{OEBA}}$) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ($\overline{\text{CEAB}}$) input must be low to enter data from A or to output data from B. If $\overline{\text{CEAB}}$ is low and $\overline{\text{LEAB}}$ is low, the A-to-B latches are transparent; a subsequent low-to-high transition of $\overline{\text{LEAB}}$ puts the A latches in the storage mode. With $\overline{\text{CEAB}}$ and $\overline{\text{OEAB}}$ both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using the $\overline{\text{CEBA}}$, $\overline{\text{LEBA}}$, and $\overline{\text{OEBA}}$ inputs.

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

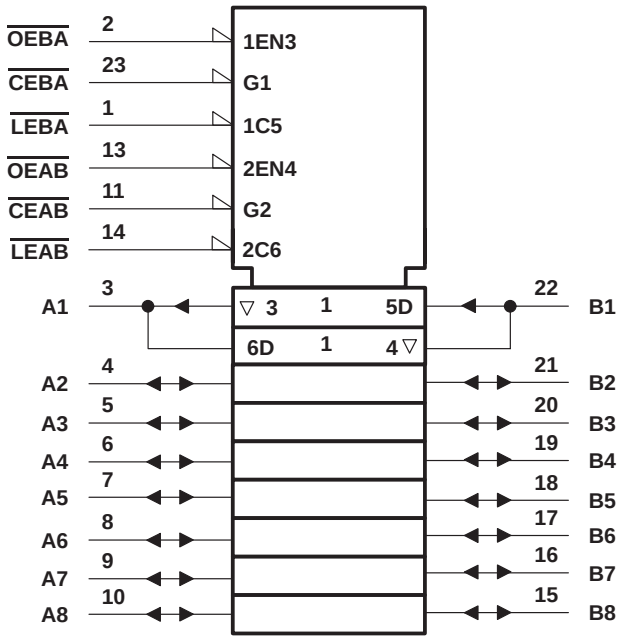
The SN54ABT543A is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74ABT543A is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

INPUTS				OUTPUT
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	B
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B_0‡
L	L	L	L	L
L	L	L	H	H

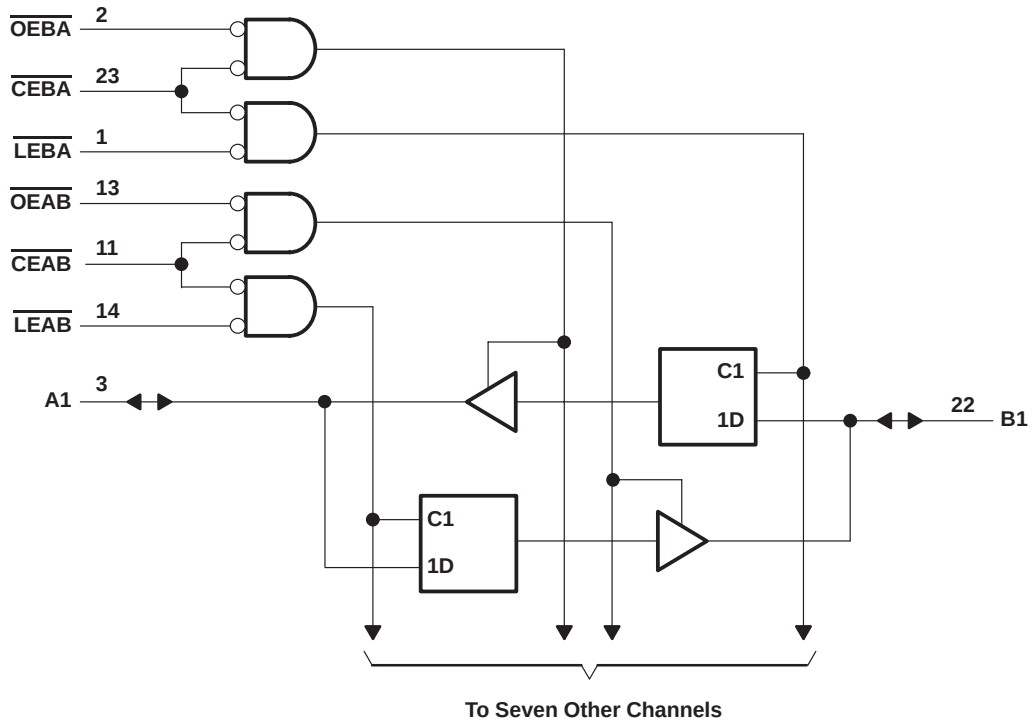
† A-to-B data flow is shown; B-to-A flow control is the same except that it uses $\overline{CEBA}$, $\overline{LEBA}$, and $\overline{OEBA}$.
‡ Output level before the indicated steady-state input conditions were established

logic symbol§



§ This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

logic diagram (positive logic)



Pin numbers shown are for the DB, DW, JT, NT, PW, and W packages.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (except I/O ports) (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, V_O . . . . . –0.5 V to 5.5 V
Current into any output in the low state, I_O: SN54ABT543A . . . . . 96 mA
SN74ABT543A . . . . . 128 mA
Input clamp current, I_{IK} ($V_I < 0$) . . . . . –18 mA
Output clamp current, I_{OK} ($V_O < 0$) . . . . . –50 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package . . . . . 104°C/W
DW package . . . . . 81°C/W
NT package . . . . . 67°C/W
PW package . . . . . 120°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. The package thermal impedance is calculated in accordance with EIA/JEDEC Std JESD51, except for through-hole packages, which use a trace length of zero.

recommended operating conditions (see Note 3)

			SN54ABT543A		SN74ABT543A		UNIT
			MIN	MAX	MIN	MAX	
V_{CC}	Supply voltage		4.5	5.5	4.5	5.5	V
V_{IH}	High-level input voltage		2		2		V
V_{IL}	Low-level input voltage			0.8		0.8	V
V_I	Input voltage		0	V_{CC}	0	V_{CC}	V
I_{OH}	High-level output current			–24		–32	mA
I_{OL}	Low-level output current			48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
T_A	Operating free-air temperature		–55	125	–40	85	°C

NOTE 3: Unused pins (input or I/O) must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		T_A = 25°C			SN54ABT543A		SN74ABT543A		UNIT
				MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2		–1.2		–1.2	V
V_{OH}		V_{CC} = 4.5 V,	I_{OH} = –3 mA	2.5			2.5		2.5		V
		V_{CC} = 5 V,	I_{OH} = –3 mA	3			3		3		
		V_{CC} = 4.5 V	I_{OH} = –24 mA	2			2				
			I_{OH} = –32 mA	2*					2		
V_{OL}		V_{CC} = 4.5 V	I_{OL} = 48 mA			0.55		0.55			V
			I_{OL} = 64 mA			0.55*				0.55	
V_{hys}					100						mV
I_I	Control inputs	V_{CC} = 5.5 V,	V_I = V_{CC} or GND			±1		±1		±1	µA
	A or B ports					±100		±100		±100	
I_{OZH}‡		V_{CC} = 5.5 V,	V_O = 2.7 V			10§		10§		10§	µA
I_{OZL}‡		V_{CC} = 5.5 V,	V_O = 0.5 V			–10§		–10§		–10§	µA
I_{off}		V_{CC} = 0,	V_I or V_O ≤ 4.5 V			±100				±100	µA
I_{CEX}		V_{CC} = 5.5 V, V_O = 5.5 V	Outputs high			50		50		50	µA
I_O¶		V_{CC} = 5.5 V,	V_O = 2.5 V	–50*	–100	–180*	–50	–200	–50	–180	mA
I_{CC}	A or B ports	V_{CC} = 5.5 V, I_O = 0, V_I = V_{CC} or GND	Outputs high		1	250*		350		250	µA
			Outputs low		24	30*		34		30	mA
			Outputs disabled		0.5	250*		350		250	µA
ΔI_{CC}#		V_{CC} = 5.5 V, One input at 3.4 V, Other inputs at V_{CC} or GND				1.5		1.5		1.5	mA
C_i	Control inputs	V_I = 2.5 V or 0.5 V			4						pF
C_{io}	A or B ports	V_O = 2.5 V or 0.5 V			7						pF

* On products compliant to MIL-PRF-38535, this parameter does not apply.
† All typical values are at V_{CC} = 5 V.
‡ The parameters I_{OZH} and I_{OZL} include the input leakage current.
§ This data sheet limit may vary among suppliers.
¶ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
# This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN54ABT543A		UNIT
				V_{CC} = 5 V, T_A = 25°C	MIN MAX	
				MIN MAX		
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low			3.5	3.5	ns
t_{su}	Setup time	Data before $\overline{LEAB}$ or $\overline{LEBA}\uparrow$	High	2.5	2.5	ns
			Low	3	3	
		Data before $\overline{CEAB}$ or $\overline{CEBA}\uparrow$	High	2.5	2.5	
			Low	3	3	
t_h	Hold time	Data after $\overline{LEAB}$ or $\overline{LEBA}\uparrow$		1	1	ns
		Data after $\overline{CEAB}$ or $\overline{CEBA}\uparrow$		1	1	

timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

				SN74ABT543A		UNIT
				V_{CC} = 5 V, T_A = 25°C	MIN MAX	
				MIN MAX		
t_w	Pulse duration, $\overline{LEAB}$ or $\overline{LEBA}$ low			3.5	3.5	ns
t_{su}	Setup time	Data before $\overline{LEAB}$ or $\overline{LEBA}\uparrow$	High	3.5	3.5	ns
			Low	3	3	
		Data before CEAB or CEBA$\uparrow$	High	3.5	3.5	
			Low	3	3	
t_h	Hold time	Data after $\overline{LEAB}$ or $\overline{LEBA}\uparrow$		0.5	0.5	ns
		Data after $\overline{CEAB}$ or $\overline{CEBA}\uparrow$		0.5	0.5	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT543A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.6†	4.4	4.4	1.6†	5.5	ns
t_{PHL}			1.6	4.4	5.1	1.6	6.2	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	1.6†	4.1	5.1	1.6†	6.6	ns
t_{PHL}			1.6	4.6	5.4	1.6	6.4	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.4	3.9	4.1	1.4	5.1	ns
t_{PZL}			2	5	4.9	2	5.8	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.5†	5.9	5.8	2.5†	6.9	ns
t_{PLZ}			2.5†	5.5	6.1	2.5†	7.6	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	1.4	3.9	4.7	1.4	5.6	ns
t_{PZL}			2	5	5.7	2	6.2	
t_{PHZ}	CEBA or CEAB	A or B	3.2†	5.9	6.5	3.2†	7.3	ns
t_{PLZ}			2.5†	5.5	6.7	2.5†	7.8	

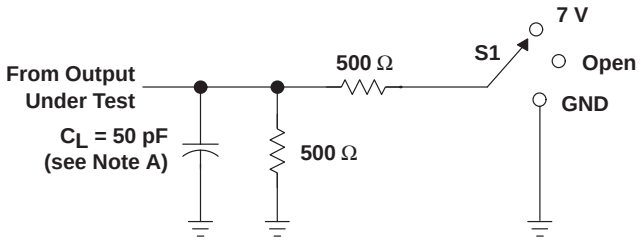
† This data sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT543A					UNIT
			V_{CC} = 5 V, T_A = 25°C			MIN	MAX	
			MIN	TYP	MAX			
t_{PLH}	A or B	B or A	1.8†	4.4	5.9	1.8†	6.9	ns
t_{PHL}			1.9	4.4	5.9	1.9	6.9	
t_{PLH}	$\overline{LEBA}$ or $\overline{LEAB}$	A or B	1.5†	4.1	5.6	1.5†	6.6	ns
t_{PHL}			2.1	4.6	6.1	2.1	7.1	
t_{PZH}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	1.4	3.9	5.4	1.4	6.4	ns
t_{PZL}			2.5	5	6.5	2.5	7.5	
t_{PHZ}	$\overline{OEBA}$ or $\overline{OEAB}$	A or B	2.5†	5.9	7.4	2.5†	8.4	ns
t_{PLZ}			2.5†	5.5	7	2.5†	8	
t_{PZH}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	1.4	3.9	5.4	1.4	6.4	ns
t_{PZL}			2.5	5	6.5	2.5	7.5	
t_{PHZ}	$\overline{CEBA}$ or $\overline{CEAB}$	A or B	2.9†	5.9	7.4	2.9†	8.4	ns
t_{PLZ}			2.4†	5.5	7	2.4†	8	

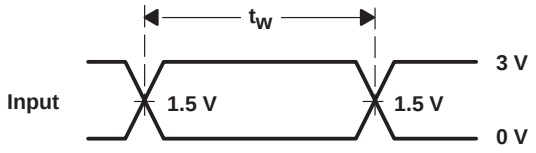
† This data sheet limit may vary among suppliers.

PARAMETER MEASUREMENT INFORMATION

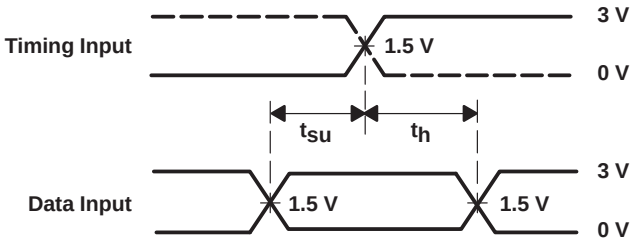


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	7 V
t_{PHZ}/t_{PZH}	Open

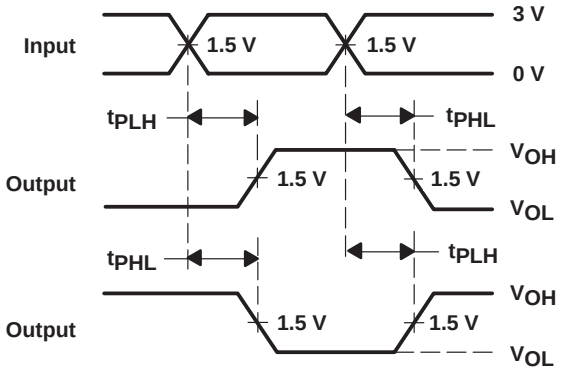
LOAD CIRCUIT



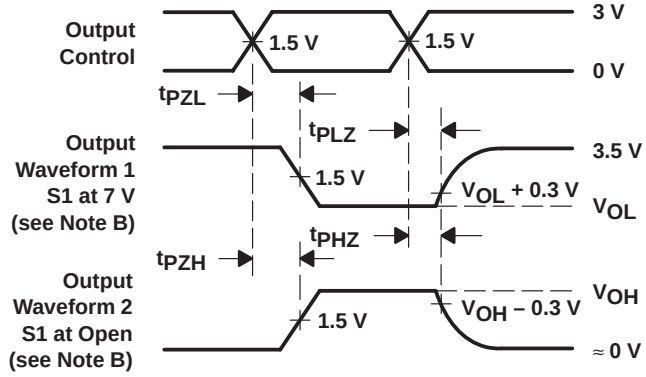
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. C_L includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
5962-9231402Q3A	Active	Production	LCCC (FK) | 28	42 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9231402Q3A SNJ54 ABT543AFK
SN74ABT543ADBR	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADBR.B	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADBRG4	Active	Production	SSOP (DB) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543ADW	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADW.B	Active	Production	SOIC (DW) | 24	25 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWR	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWR.B	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWRG4	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543ADWRG4.B	Active	Production	SOIC (DW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT543A
SN74ABT543APW	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APW.B	Active	Production	TSSOP (PW) | 24	60 | TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APWR	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SN74ABT543APWR.B	Active	Production	TSSOP (PW) | 24	2000 | LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB543A
SNJ54ABT543AFK	Active	Production	LCCC (FK) | 28	42 | TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9231402Q3A SNJ54 ABT543AFK

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54ABT543A, SN74ABT543A :

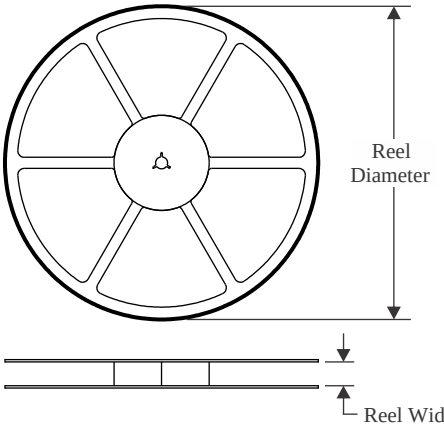
- Catalog : SN74ABT543A
- Military : SN54ABT543A

NOTE: Qualified Version Definitions:

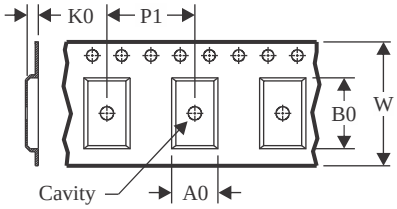
- Catalog - TI's standard catalog product
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

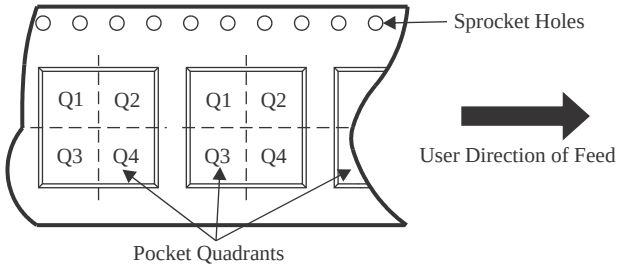


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

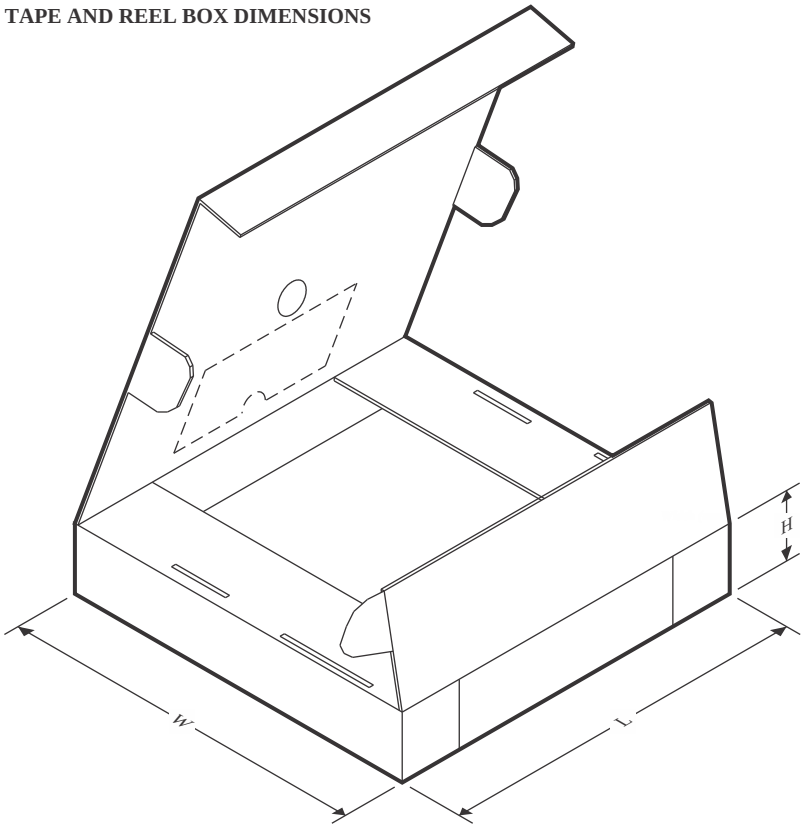
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT543ADBR	SSOP	DB	24	2000	330.0	16.4	8.2	8.8	2.5	12.0	16.0	Q1
SN74ABT543ADWR	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543ADWRG4	SOIC	DW	24	2000	330.0	24.4	10.75	15.7	2.7	12.0	24.0	Q1
SN74ABT543APWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

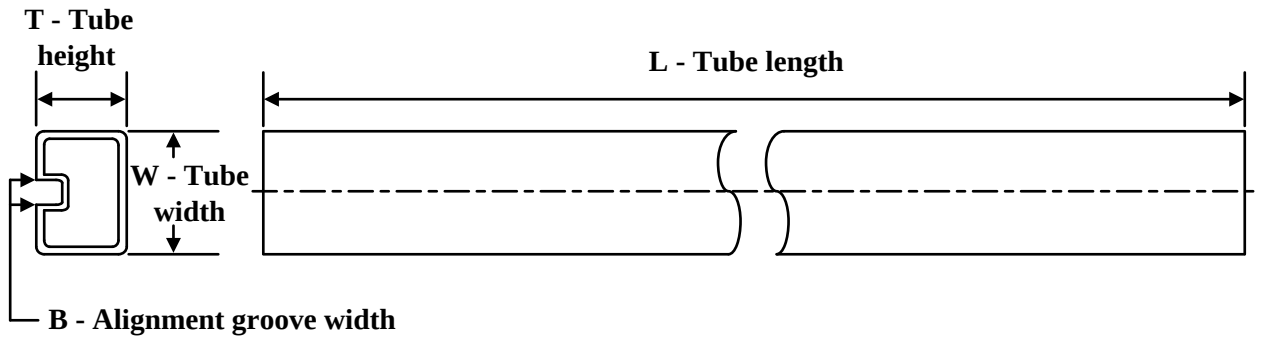
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT543ADBR	SSOP	DB	24	2000	353.0	353.0	32.0
SN74ABT543ADWR	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT543ADWRG4	SOIC	DW	24	2000	350.0	350.0	43.0
SN74ABT543APWR	TSSOP	PW	24	2000	353.0	353.0	32.0

TUBE

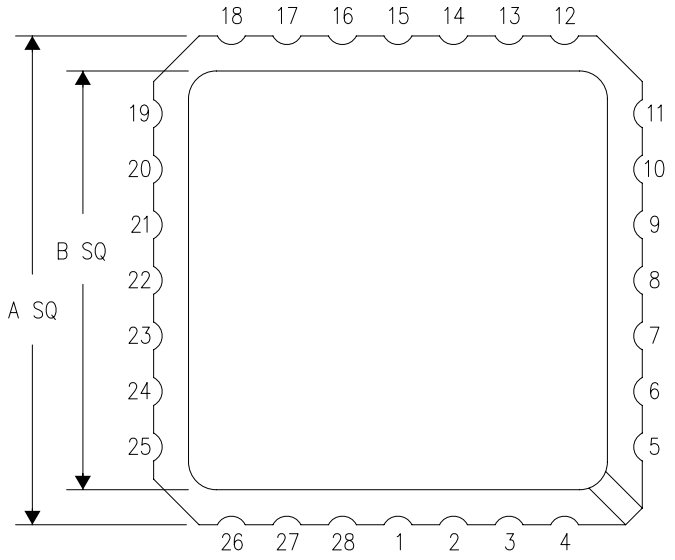


*All dimensions are nominal

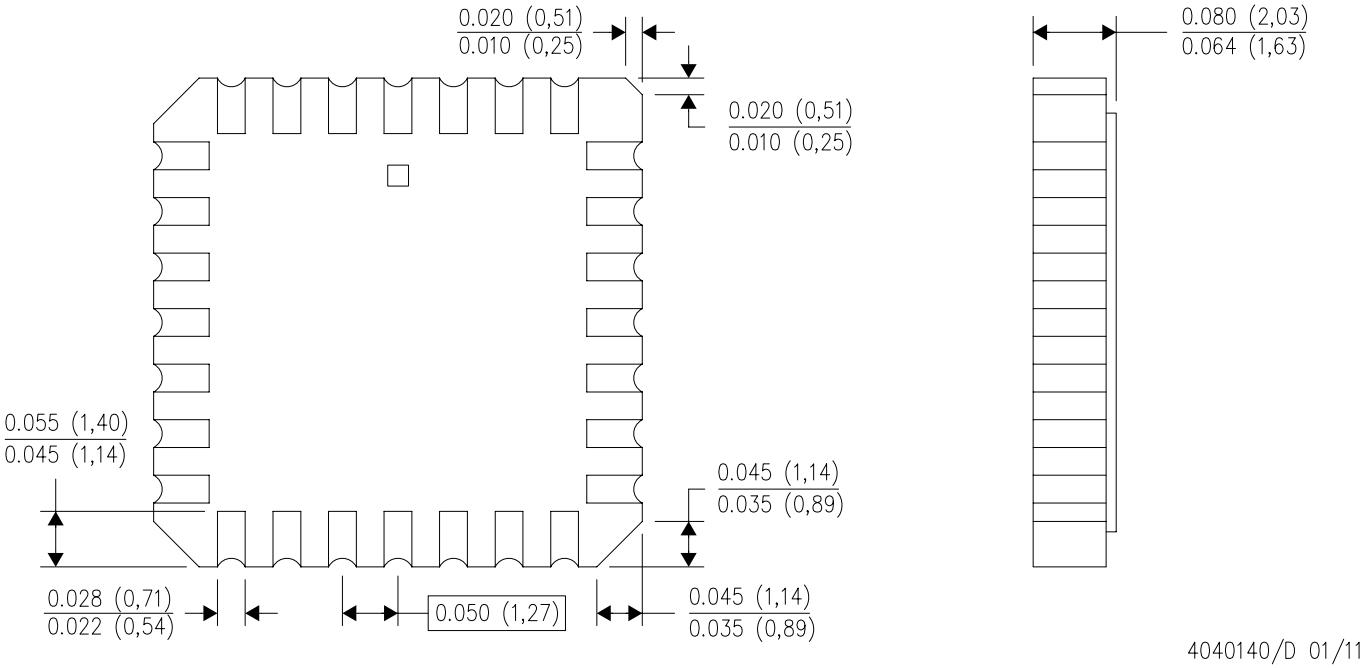
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ABT543ADW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT543ADW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74ABT543APW	PW	TSSOP	24	60	530	10.2	3600	3.5
SN74ABT543APW.B	PW	TSSOP	24	60	530	10.2	3600	3.5

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



4040140/D 01/11

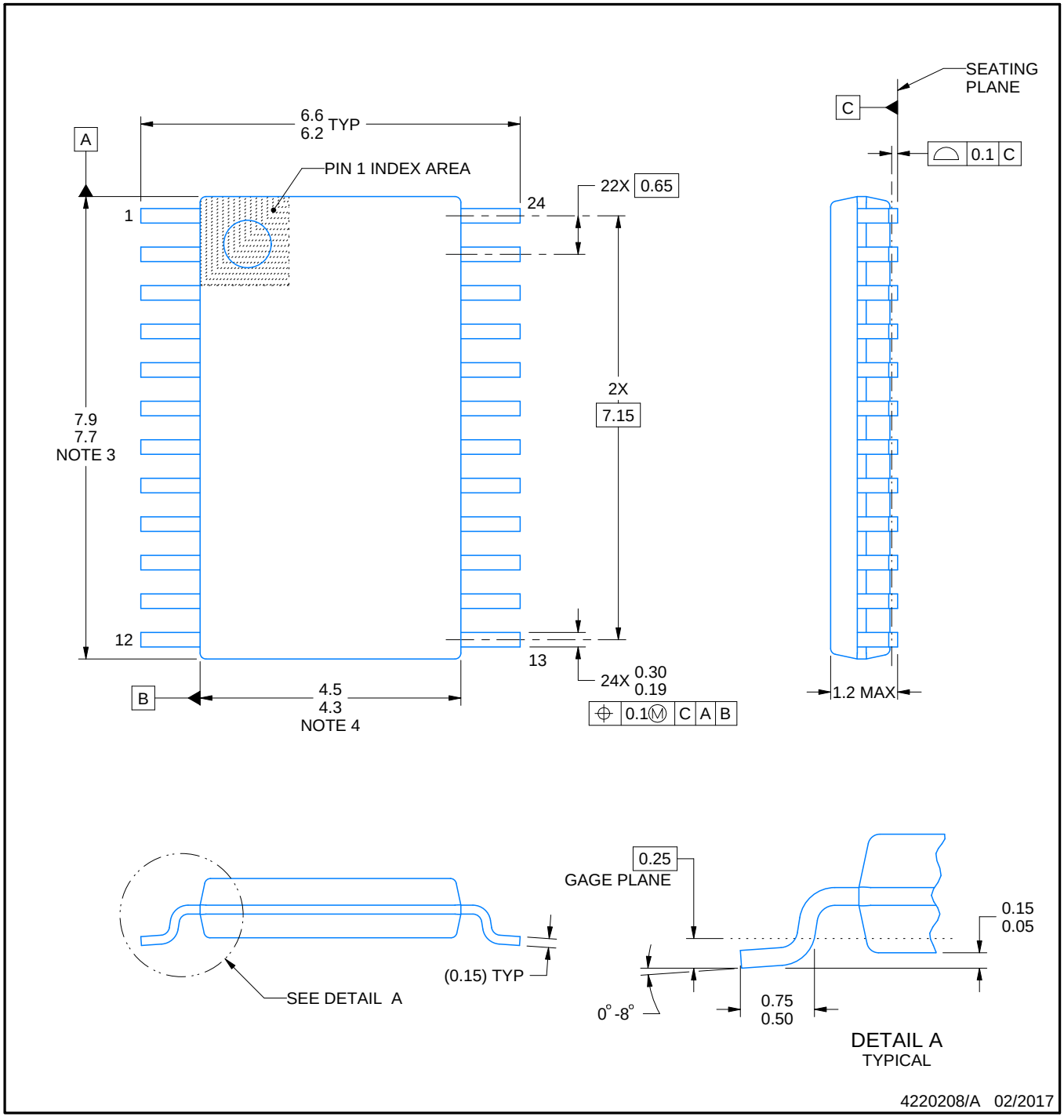
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

PACKAGE OUTLINE

PW0024A

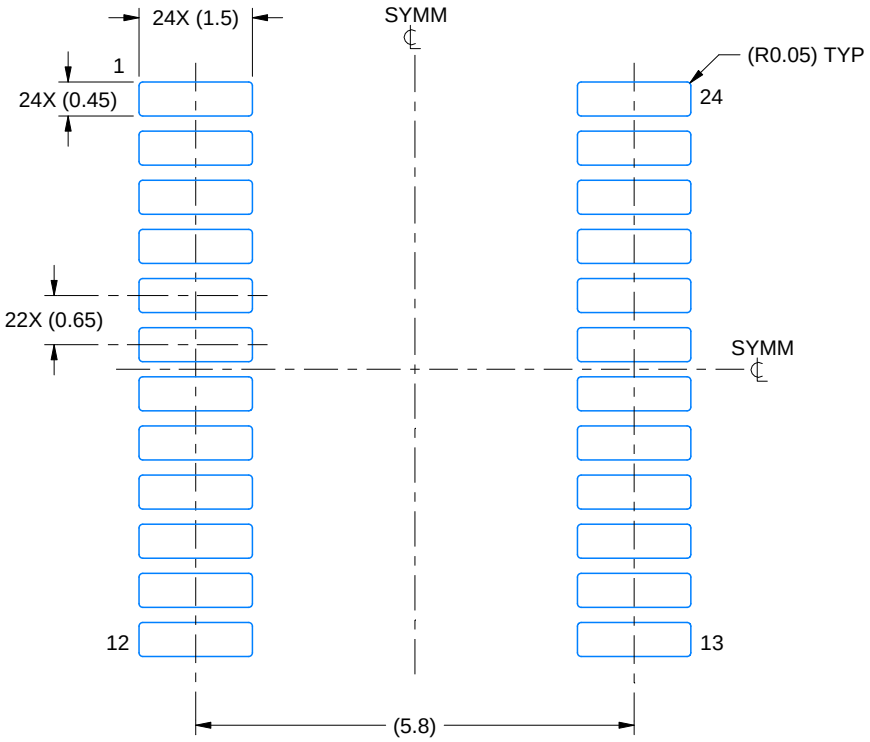
TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE

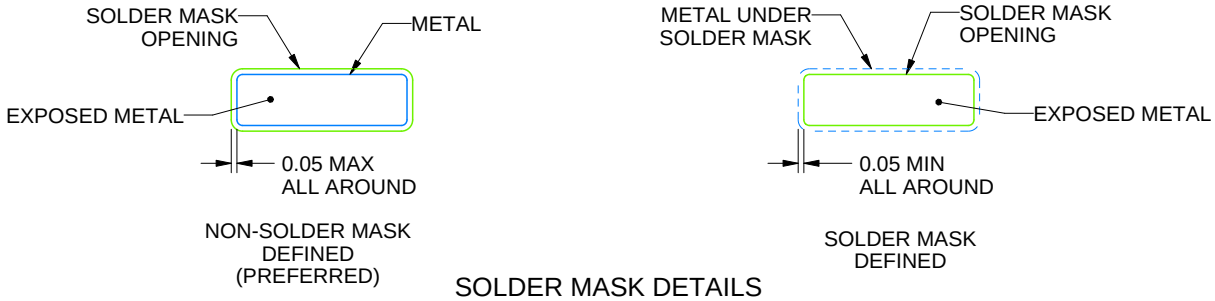


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

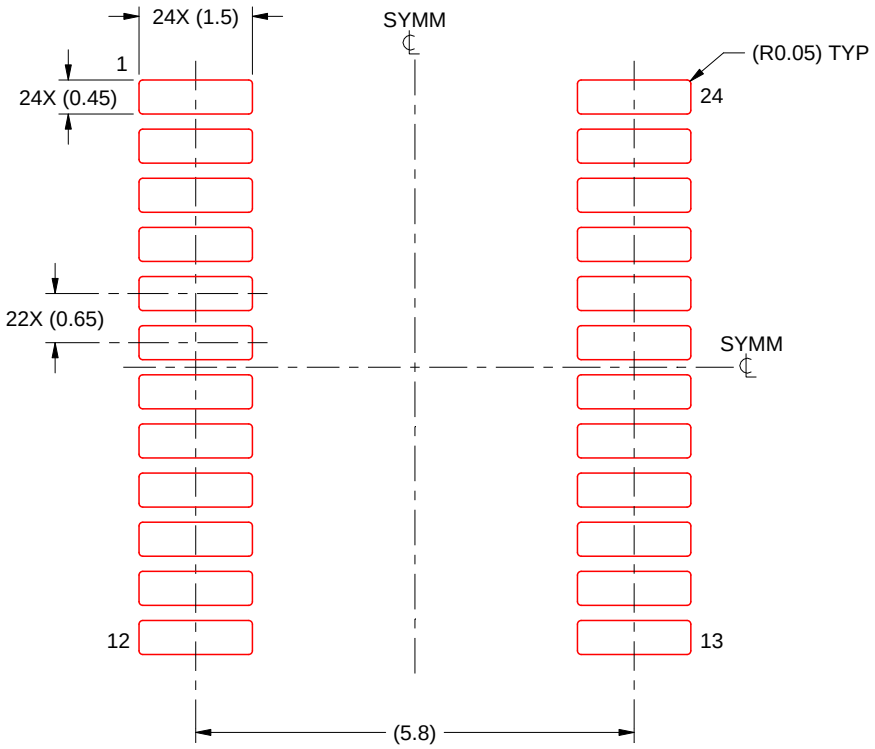


SOLDER MASK DETAILS

4220208/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



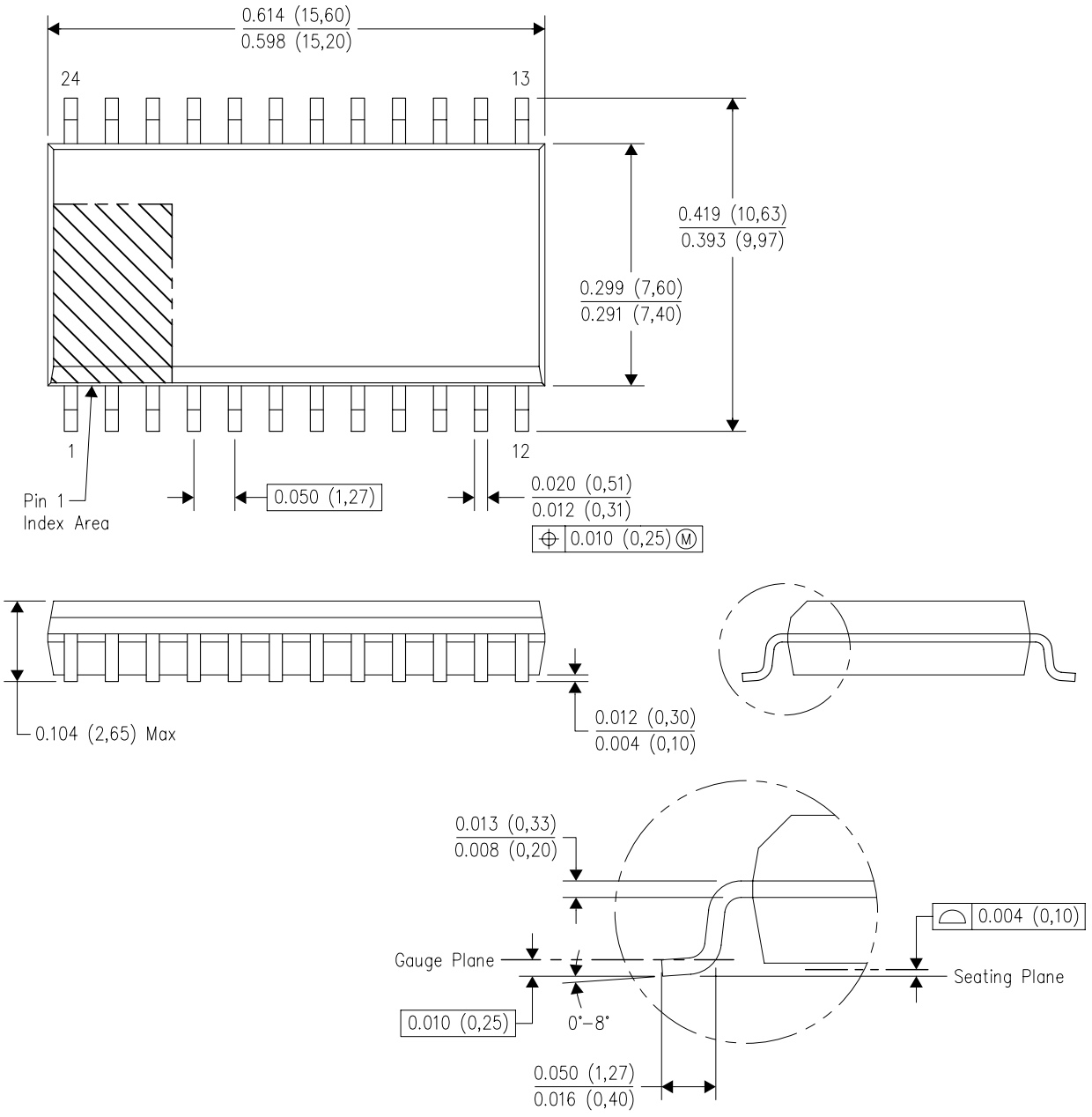
SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220208/A 02/2017

NOTES: (continued)

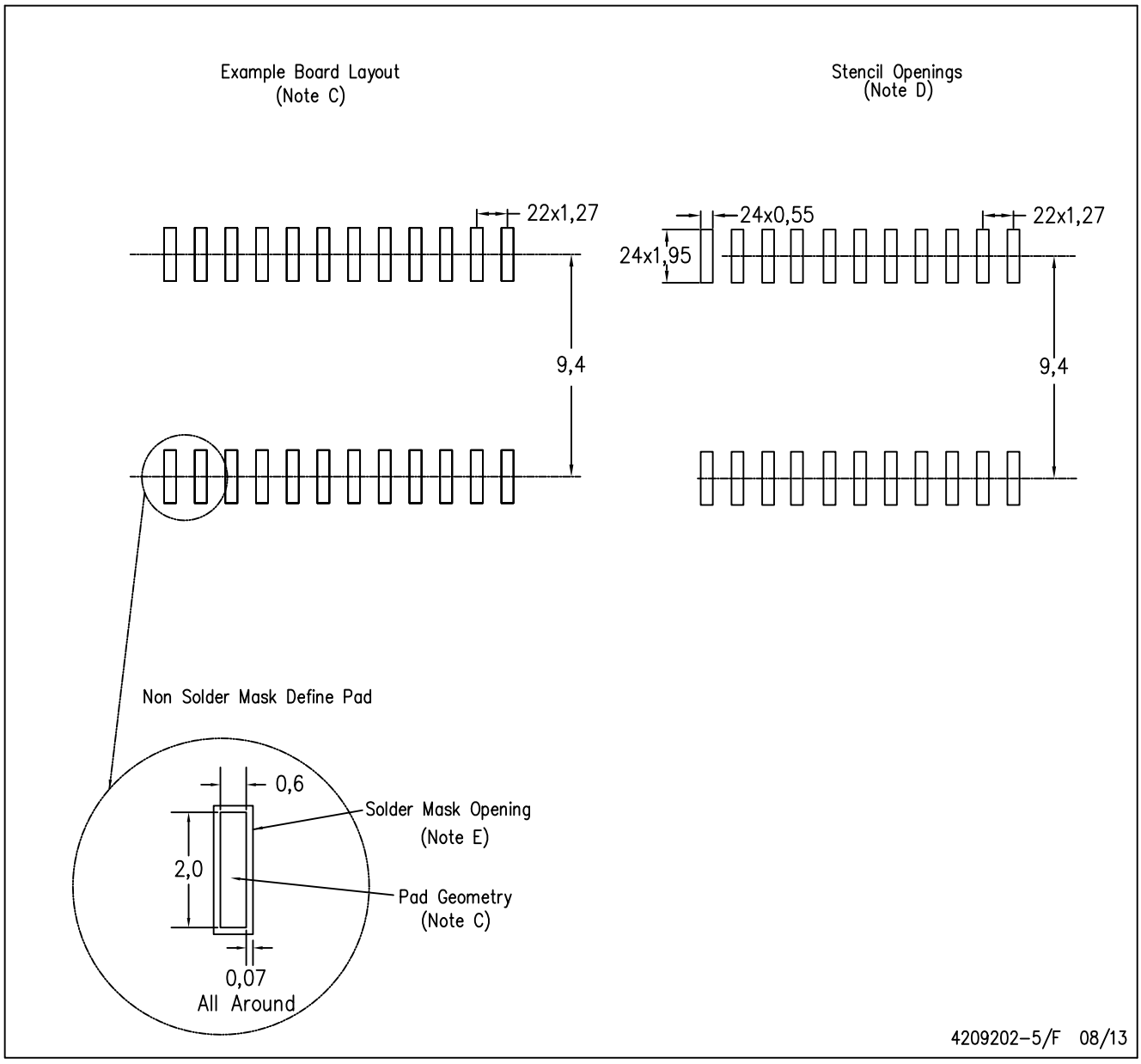
8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
D. Falls within JEDEC MS–013 variation AD.

DW (R–PDSO–G24) PLASTIC SMALL OUTLINE

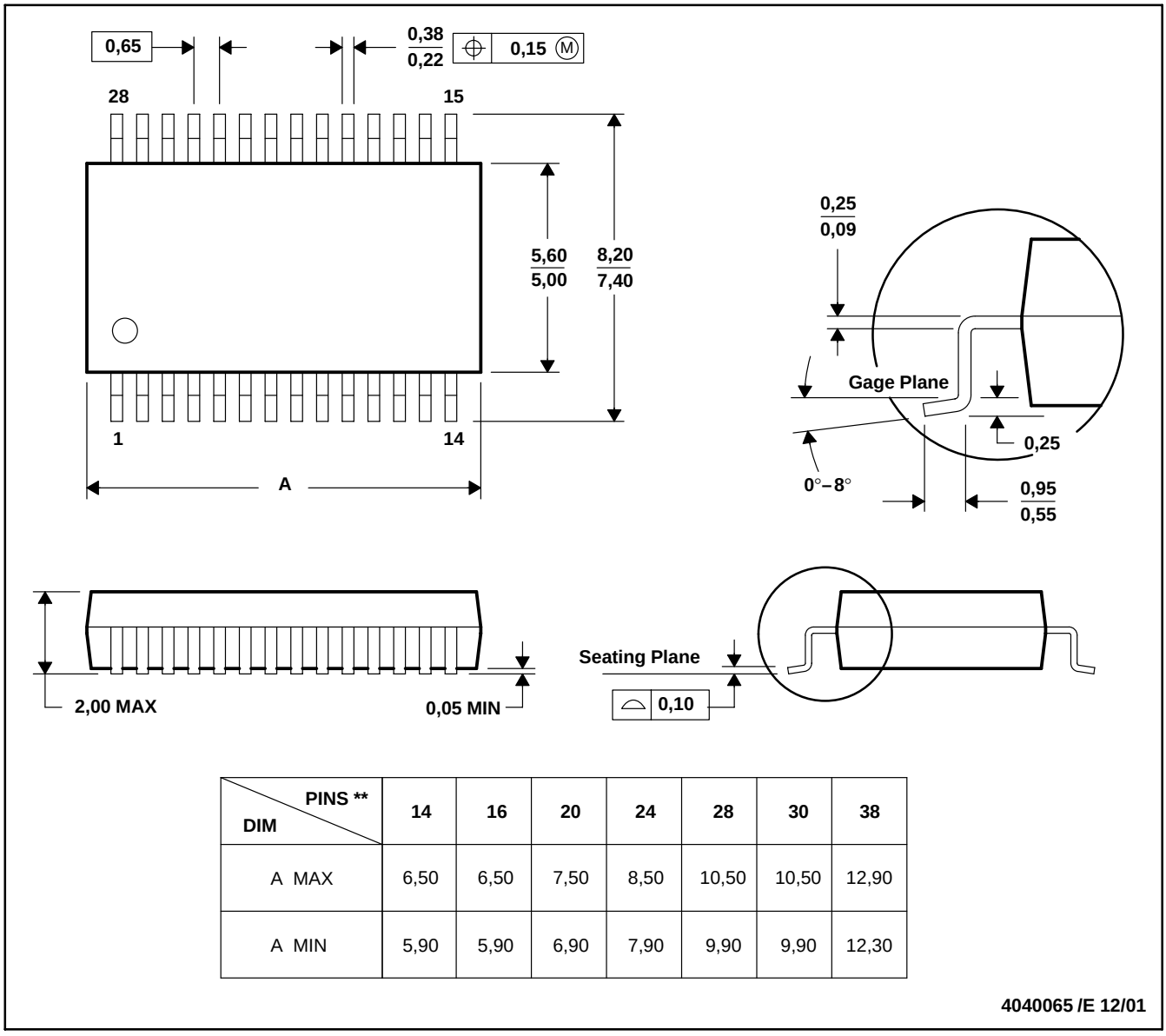


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Refer to IPC7351 for alternate board design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MSSO002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G)** **PLASTIC SMALL-OUTLINE**

28 PINS SHOWN



DIM \ PINS **	14	16	20	24	28	30	38
A MAX	6,50	6,50	7,50	8,50	10,50	10,50	12,90
A MIN	5,90	5,90	6,90	7,90	9,90	9,90	12,30

4040065 /E 12/01

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
D. Falls within JEDEC MO-150

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Last updated 10/2025